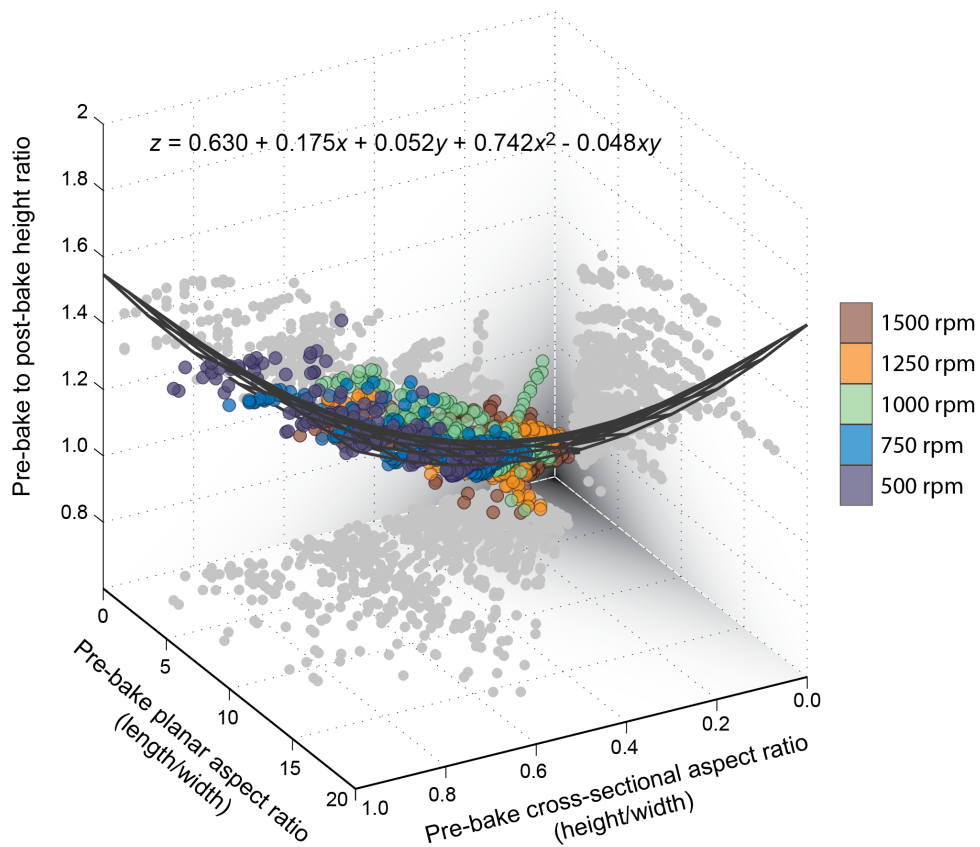


Supplementary Figure 1. Reflow has little effect on feature lengths. **(A)** Measured pre- and post-bake feature lengths as a function of design feature length for wafers spun at 500, 750, 1000, 1250, and 1500 rpm. All lengths in this figure were measured via image analysis as described in the main text. **(B)** Normalized measured pre-bake length as a function of design feature length. **(C)** Normalized post-bake length as a function of design feature length. **(D)** Relative change in length after baking (measured post-bake length/measured pre-bake length) as a function of design feature length.



Supplementary Figure 2. Polynomial model of post-bake feature heights as a function of pre-bake aspect ratios. Three-dimensional plot shows the height ratio as a function of both the pre-bake cross-sectional aspect ratio (measured height/width) and pre-bake planar aspect ratio (measured length/width). The black line corresponds to an on-edge view of a surface fit to the data, given by the polynomial shown in the figure and described in the text. All data points are colored according to the photoresist spin speed.